

EDAPS 2023 (Hybrid) Call for Papers

**Sugar Beach Resort, Wolmar, Flic-en-Flac
Republic of Mauritius | Dec. 12 -14th, 2023**

IEEE EDAPS

The IEEE Electrical Design of Advanced Packaging and Systems (EDAPS) Symposium is the premier international conference in Asia-Pacific to share the recent progress of design, modeling, simulation, and measurement related to the electrical issues arising at the chip, package, and system levels. Covering the paper and poster presentations, keynotes, and tutorials, EDAPS 2023 will be held in the paradise island of **Mauritius, December 12-14, 2023**. For further information, please visit the website at **edaps.org**

Paper Submission

Papers should be submitted electronically in two-column and three-page PDF file format through the EDAPS website (**www.edaps.org**). A Microsoft Word template is available on the symposium website. Hardcopy submissions will NOT be accepted. Submitted manuscripts should be camera ready and compliant with the general standards of the IEEE, including appropriate referencing. Only compliant manuscripts will be considered for review.

Awards | Travel Grants | Special Issue

- ❑ Best Paper Award | Best Student Paper Award | Best Poster Award
- ❑ Regional & International Student Travel Grants
- ❑ Selected Papers will be invited for a Special Issue in IEEE Transactions on Components, Packaging, and Manufacturing Technology (IEEE TCPMT)

<https://eps.ieee.org/publications/ieee-transactions-on-cpmt.html>

Important Dates

Manuscript Submission Deadline: September 29th, 2023

Notification of Acceptance: October 20th, 2023

Conference Date: December 12th-14th, 2023

Conference Topics

- 3D-ICs / TSVs / Interposers/Heterogeneous Integration
- Testing on 3D-IC and SiP
- Signal, Power, EMI, and Thermal Integrity
- Multi-physics Simulation Techniques
- Design and Modeling for High-speed Channels
- Electronic Packages, SiP / SoP
- IC and Package Level EMC
- RF/mm-wave Packages
- Power Electronic Packages
- Advanced Simulation Tools and CAD
- Electrical Design of Flexible Devices & Sensing, 5G Wireless Communication
- Substrate Technology for Packages & PCBs
- 2-D Materials for 3D-ICs and SiP
- Electrical Machines, Automation, Instrumentation and Control, Mechatronics and Robotics
- Smart Grid, Renewable Energy, Energy Efficiency and Storage Technologies
- Power Systems and Power Electronics
- Digital Signal and Image Processing, Logic Design and Embedded systems
- AI, Machine Learning and IoT Applications
- Communications Theory, Networking, Mobile and Wireless Communications
- Engineering solutions to UN SDGs, Climate Change and Circular Economy

Conference Co-Chairs

Rajen Murugan, Texas Instruments, Inc.
Dipanjan Gope, India Institute of Science, IISc

Local Organizing Committee Co-Chairs

Tulsi Pawan Fowdur, University of Mauritius
Robert T.F. Ah King, University of Mauritius
Mahendra Gooroochurn, University of Mauritius

Local Organizing Committee Members

Bhimsen Rajkumarsingh, University of Mauritius
Vandana Bassoo, University of Mauritius
Vikash Oree, University of Mauritius
Rajeshree Ballgobin, University of Mauritius
A. P. Murdan, University of Mauritius
M. A. Hosany, University of Mauritius

International Conference Advisors

Madhavan Swaminathan, Penn State University, USA
Jose Schutt-Aine, University of Illinois, USA
Nikita Ambasana, Intel, India
Rohit Sharma, IIT Ropar, India
Tanja Braun, Fraunhofer Institute, Germany
Stefano Grivet-Talocia, Politecnico di Torino, Italy



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